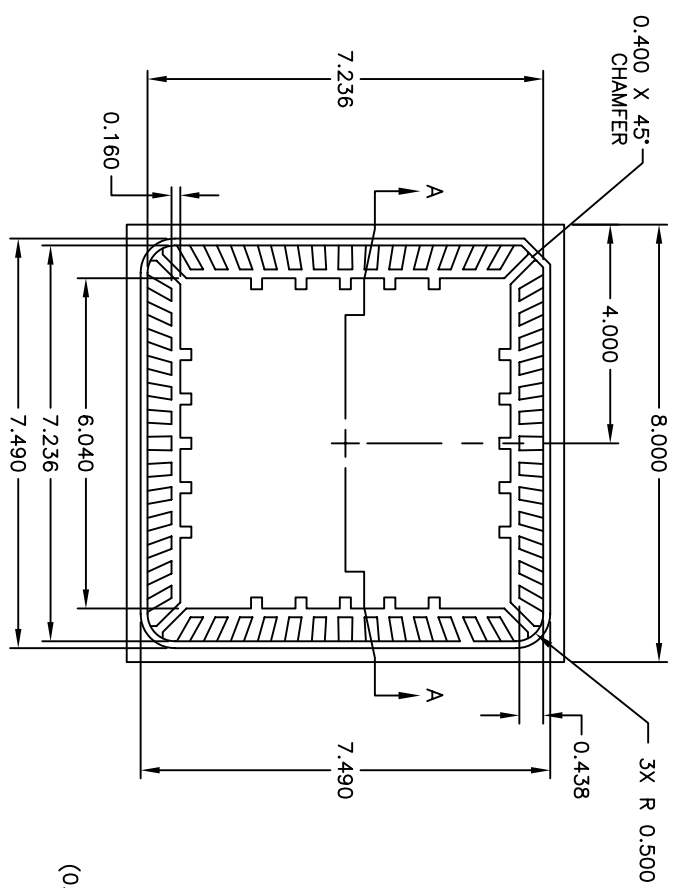
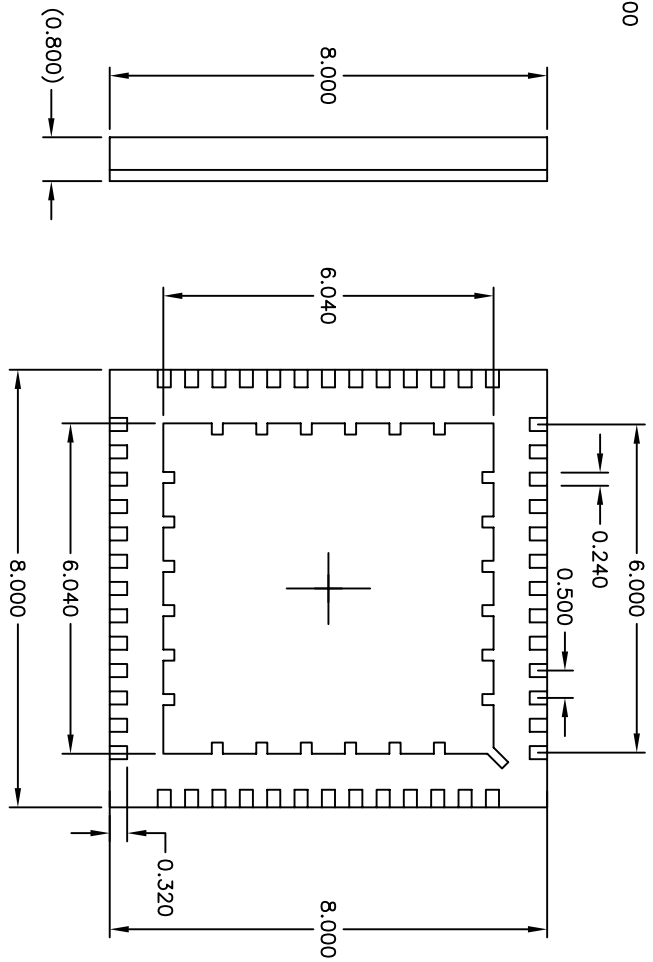


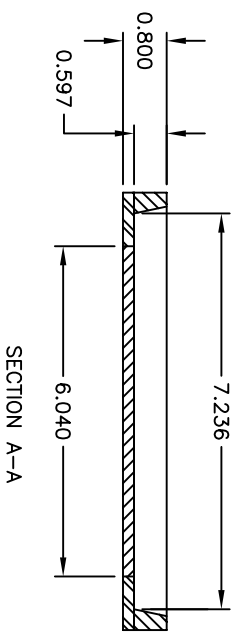
REVISIONS		
ECON NO.	DATE	DESCRIPTION
10732	08/11/06	PRODUCTION RELEASE
		APPROVED
		D.BENANDIO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FINISH: FULL GOLD PLATE.
  3. LEAD FRAME: COPPER, 194 FH.
  4. LEAD FINISH: FULL GOLD PLATE.
  5. FRAME THICKNESS: 0.2030 ± 0.0076.
  6. DIE PAD: 6.040 X 6.040.
  7. JEDEC OUTLINE: MO-220 (VLLD-1).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

TOLERANCES ARE: XXXX ± 0.15 XXXX ± 0.10 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	8/11/06
APP BY	P. FLASKERUD	DATE	8/11/06
CUSTOMER	---		

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 PHONE: (408) 400-9002 FAX: (408) 400-9006

52 Lead 8mm x 8mm  
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP8X8-52-0P-01	1
SCALE	NONE	
CAD FILE	MLP8X8-52-0P-01-RL.DWG	
SHEET	1 OF 1	